

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0003] with the following new paragraph:

[0003] Generally, the various process steps required for manufacturing semiconductor devices are broadly grouped into the fabrication steps required to form semiconductor chips on a semiconductor wafer, the packaging steps required to separate the individual semiconductor chips and mount the chip or chips in a package and the testing steps required for confirming the functionality of the completed semiconductor package. The packaging steps include steps for sawing the semiconductor wafer to divide the semiconductor elements formed in the wafer into individual chips, attaching the individual chips to die pads provided on a series of leadframes, wire-bonding to ~~from-form~~ electrical connections between the chip bonding pads and the leadframe inner leads, encapsulating the individual chips with a molding compound, plating the outer leadframe leads with solder and bending, cutting or otherwise forming the plated outer leads into the desired configuration to form discrete packages.

Please replace paragraph [0031] with the following new paragraph:

[0031] As illustrated in FIGS. 7-10, the protective tape 206 is adhered to the upper surface of the wafer 204 to protect the circuit area of the chips formed on the upper surface of the wafer. A backside grinding process is then performed to thin wafer ~~203~~204, after which the thinned wafer is fixed to a jig 202 or other wafer carrier assembly by the adhesive tape 200 or by vacuum applied to the backside of the wafer (not shown). The fixed wafer 204 is then transferred to a wafer sawing station (as generally illustrated in FIG. 2) by a transfer mechanism or combination of mechanisms (not shown).

SPECIFICATION

[Title of the Invention]

5 **Protection tape removing apparatus and method of assembling semiconductor package using the same**

[Brief Description of the Drawings]

10 **FIGS. 1 through 4 are a cross-sectional view and perspective views for explaining a conventional method of assembling a semiconductor package;**

FIG. 5 is a flowchart for explaining a conventional method of assembling a semiconductor package;

FIG. 6 is a flowchart for explaining a method of assembling a semiconductor package according to the present invention;

15 **FIGS. 7 through 10 are cross-sectional views for explaining a method of assembling a semiconductor package according to the present invention;**

FIGS. 11 and 12 are cross-sectional views for explaining a protection tape removing apparatus according to the present invention; and

20 **FIG. 13 is a cross-sectional view for explaining a protection tape removing apparatus according to the present invention.**

< Explanation of Reference numerals designating the Major Elements of the Drawings >

200; Adhesive tape	202; Jig
204; Individual chip	206, 206'; Protection tape
208; Blade	210; Frame
25 212; UV lamp	302; Body
304; Supply roll	306; Winding roll
308; Release tape	310; Pressure pin
312; Guide roller	314; Pressure roller
316; Pressure surface	

30 **[Detailed Description of the Invention]**